

Abstract

385

Electronic Module, in Particular a Multichip Module,
Comprising a Multilayer Wiring and Method of Making the
Same

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The component side of the multilayer wiring (2) adheres
with its component-free portions to the hermetic case
(4), and the bottom side of the multilayer wiring (2)
having a height of less than approx. 100 μm , directly,
395 i.e. without additional wiring substrate (1), consti-
tutes the bottom side of the module.

Figure 1